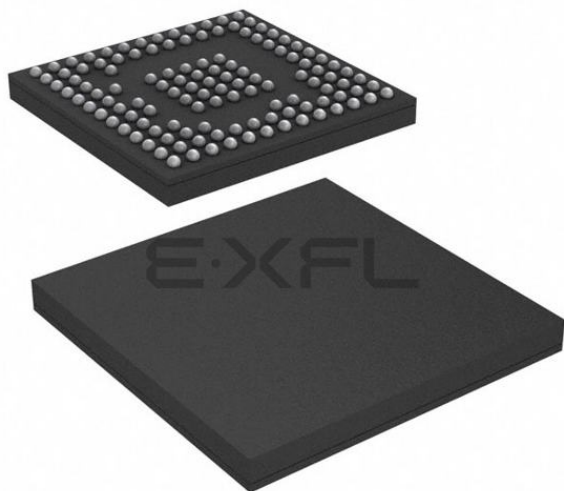




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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I ² C, IrDA, LINbus, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I ² S, POR, PWM, WDT
Number of I/O	65
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D - 12b SAR
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	125-VFBGA
Supplier Device Package	125-BGA (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32pg12b500f1024gl125-c

3.5.4 Low Energy Timer (LETIMER)

The unique LETIMER is a 16-bit timer that is available in energy mode EM2 Deep Sleep in addition to EM1 Sleep and EM0 Active. This allows it to be used for timing and output generation when most of the device is powered down, allowing simple tasks to be performed while the power consumption of the system is kept at an absolute minimum. The LETIMER can be used to output a variety of waveforms with minimal software intervention. The LETIMER is connected to the Real Time Counter and Calendar (RTCC), and can be configured to start counting on compare matches from the RTCC.

3.5.5 Ultra Low Power Wake-up Timer (CRYOTIMER)

The CRYOTIMER is a 32-bit counter that is capable of running in all energy modes. It can be clocked by either the 32.768 kHz crystal oscillator (LFXO), the 32.768 kHz RC oscillator (LFRCO), or the 1 kHz RC oscillator (ULFRCO). It can provide periodic Wakeup events and PRS signals which can be used to wake up peripherals from any energy mode. The CRYOTIMER provides a wide range of interrupt periods, facilitating flexible ultra-low energy operation.

3.5.6 Pulse Counter (PCNT)

The Pulse Counter (PCNT) peripheral can be used for counting pulses on a single input or to decode quadrature encoded inputs. The clock for PCNT is selectable from either an external source on pin PCTn_S0IN or from an internal timing reference, selectable from among any of the internal oscillators, except the AUXHFRCO. The module may operate in energy mode EM0 Active, EM1 Sleep, EM2 Deep Sleep, and EM3 Stop.

3.5.7 Watchdog Timer (WDOG)

The watchdog timer can act both as an independent watchdog or as a watchdog synchronous with the CPU clock. It has windowed monitoring capabilities, and can generate a reset or different interrupts depending on the failure mode of the system. The watchdog can also monitor autonomous systems driven by PRS.

3.6 Communications and Other Digital Peripherals

3.6.1 Universal Synchronous/Asynchronous Receiver/Transmitter (USART)

The Universal Synchronous/Asynchronous Receiver/Transmitter is a flexible serial I/O module. It supports full duplex asynchronous UART communication with hardware flow control as well as RS-485, SPI, MicroWire and 3-wire. It can also interface with devices supporting:

- ISO7816 SmartCards
- IrDA
- I²S

3.6.2 Low Energy Universal Asynchronous Receiver/Transmitter (LEUART)

The unique LEUARTTM provides two-way UART communication on a strict power budget. Only a 32.768 kHz clock is needed to allow UART communication up to 9600 baud. The LEUART includes all necessary hardware to make asynchronous serial communication possible with a minimum of software intervention and energy consumption.

3.6.3 Inter-Integrated Circuit Interface (I²C)

The I²C module provides an interface between the MCU and a serial I²C bus. It is capable of acting as both a master and a slave and supports multi-master buses. Standard-mode, fast-mode and fast-mode plus speeds are supported, allowing transmission rates from 10 kbit/s up to 1 Mbit/s. Slave arbitration and timeouts are also available, allowing implementation of an SMBus-compliant system. The interface provided to software by the I²C module allows precise timing control of the transmission process and highly automated transfers. Automatic recognition of slave addresses is provided in active and low energy modes.

3.6.4 Peripheral Reflex System (PRS)

The Peripheral Reflex System provides a communication network between different peripheral modules without software involvement. Peripheral modules producing Reflex signals are called producers. The PRS routes Reflex signals from producers to consumer peripherals which in turn perform actions in response. Edge triggers and other functionality can be applied by the PRS. The PRS allows peripheral to act autonomously without waking the MCU core, saving power.

4.1.3 Thermal Characteristics

Table 4.3. Thermal Characteristics

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Thermal Resistance	THETA _{JA}	QFN48 Package, 2-Layer PCB, Air velocity = 0 m/s	—	75.7	—	°C/W
		QFN48 Package, 2-Layer PCB, Air velocity = 1 m/s	—	61.5	—	°C/W
		QFN48 Package, 2-Layer PCB, Air velocity = 2 m/s	—	55.4	—	°C/W
		QFN48 Package, 4-Layer PCB, Air velocity = 0 m/s	—	30.2	—	°C/W
		QFN48 Package, 4-Layer PCB, Air velocity = 1 m/s	—	26.3	—	°C/W
		QFN48 Package, 4-Layer PCB, Air velocity = 2 m/s	—	24.9	—	°C/W
		BGA125 Package, 2-Layer PCB, Air velocity = 0 m/s	—	90.7	—	°C/W
		BGA125 Package, 2-Layer PCB, Air velocity = 1 m/s	—	73.7	—	°C/W
		BGA125 Package, 2-Layer PCB, Air velocity = 2 m/s	—	66.4	—	°C/W
		BGA125 Package, 4-Layer PCB, Air velocity = 0 m/s	—	45	—	°C/W
		BGA125 Package, 4-Layer PCB, Air velocity = 1 m/s	—	39.6	—	°C/W
		BGA125 Package, 4-Layer PCB, Air velocity = 2 m/s	—	37.6	—	°C/W

4.1.4 DC-DC Converter

Test conditions: $L_{DCDC}=4.7\ \mu\text{H}$ (Murata LQH3NPN4R7MM0L), $C_{DCDC}=4.7\ \mu\text{F}$ (Samsung CL10B475KQ8NQNC), $V_{DCDC_I}=3.3\ \text{V}$, $V_{DCDC_O}=1.8\ \text{V}$, $I_{DCDC_LOAD}=50\ \text{mA}$, Heavy Drive configuration, $F_{DCDC_LN}=7\ \text{MHz}$, unless otherwise indicated.

Table 4.4. DC-DC Converter

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input voltage range	V_{DCDC_I}	Bypass mode, $I_{DCDC_LOAD} = 50\ \text{mA}$	1.8	—	$V_{VREGVDD_MAX}$	V
		Low noise (LN) mode, 1.8 V output, $I_{DCDC_LOAD} = 100\ \text{mA}$, or Low power (LP) mode, 1.8 V output, $I_{DCDC_LOAD} = 10\ \text{mA}$	TBD	—	$V_{VREGVDD_MAX}$	V
		Low noise (LN) mode, 1.8 V output, $I_{DCDC_LOAD} = 200\ \text{mA}$	TBD	—	$V_{VREGVDD_MAX}$	V
Output voltage programmable range ¹	V_{DCDC_O}		1.8	—	$V_{VREGVDD}$	V
Regulation DC accuracy	ACC_{DC}	Low Noise (LN) mode, 1.8 V target output	TBD	—	TBD	V
Regulation window ⁴	WIN_{REG}	Low Power (LP) mode, $LPCMPBIASEM_{xx^3} = 0$, 1.8 V target output, $I_{DCDC_LOAD} \leq 75\ \mu\text{A}$	TBD	—	TBD	V
		Low Power (LP) mode, $LPCMPBIASEM_{xx^3} = 3$, 1.8 V target output, $I_{DCDC_LOAD} \leq 10\ \text{mA}$	TBD	—	TBD	V
Steady-state output ripple	V_R		—	3	—	mVpp
Output voltage under/overshoot	V_{OV}	CCM Mode ($LNFORCECCM^3 = 1$), Load changes between 0 mA and 100 mA	—	—	TBD	mV
		DCM Mode ($LNFORCECCM^3 = 0$), Load changes between 0 mA and 10 mA	—	—	TBD	mV
		Overshoot during LP to LN CCM/DCM mode transitions compared to DC level in LN mode	—	200	—	mV
		Undershoot during BYP/LP to LN CCM ($LNFORCECCM^3 = 1$) mode transitions compared to DC level in LN mode	—	50	—	mV
		Undershoot during BYP/LP to LN DCM ($LNFORCECCM^3 = 0$) mode transitions compared to DC level in LN mode	—	125	—	mV
DC line regulation	V_{REG}	Input changes between $V_{VREGVDD_MAX}$ and 2.4 V	—	0.1	—	%
DC load regulation	I_{REG}	Load changes between 0 mA and 100 mA in CCM mode	—	0.1	—	%

4.1.5.3 Current Consumption 1.8 V without DC-DC Converter

Unless otherwise indicated, typical conditions are: VREGVDD = AVDD = DVDD = 1.8 V. T_{OP} = 25 °C. DCDC is off. Minimum and maximum values in this table represent the worst conditions across supply voltage and process variation at T_{OP} = 25 °C.

Table 4.7. Current Consumption 1.8 V without DC-DC Converter

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Current consumption in EM0 mode with all peripherals disabled	I _{ACTIVE}	38.4 MHz crystal, CPU running while loop from flash ¹	—	126	—	μA/MHz
		38 MHz HFRCO, CPU running Prime from flash	—	99	—	μA/MHz
		38 MHz HFRCO, CPU running while loop from flash	—	99	—	μA/MHz
		38 MHz HFRCO, CPU running CoreMark from flash	—	124	—	μA/MHz
		26 MHz HFRCO, CPU running while loop from flash	—	102	—	μA/MHz
		1 MHz HFRCO, CPU running while loop from flash	—	277	—	μA/MHz
Current consumption in EM0 mode with all peripherals disabled and voltage scaling enabled	I _{ACTIVE_VS}	19 MHz HFRCO, CPU running while loop from flash	—	87	—	μA/MHz
		1 MHz HFRCO, CPU running while loop from flash	—	231	—	μA/MHz
Current consumption in EM1 mode with all peripherals disabled	I _{EM1}	38.4 MHz crystal ¹	—	76	—	μA/MHz
		38 MHz HFRCO	—	50	—	μA/MHz
		26 MHz HFRCO	—	52	—	μA/MHz
		1 MHz HFRCO	—	227	—	μA/MHz
Current consumption in EM1 mode with all peripherals disabled and voltage scaling enabled	I _{EM1_VS}	19 MHz HFRCO	—	47	—	μA/MHz
		1 MHz HFRCO	—	190	—	μA/MHz
Current consumption in EM2 mode, with voltage scaling enabled.	I _{EM2_VS}	Full 256 kB RAM retention and RTCC running from LFXO	—	2.8	—	μA
		Full 256 kB RAM retention and RTCC running from LFRCO	—	3.0	—	μA
		16 kB (1 bank) RAM retention and RTCC running from LFRCO ²	—	1.9	—	μA
Current consumption in EM3 mode, with voltage scaling enabled.	I _{EM3_VS}	Full 256 kB RAM retention and CRYOTIMER running from ULFR-CO	—	2.47	—	μA
Current consumption in EM4H mode, with voltage scaling enabled.	I _{EM4H_VS}	128 byte RAM retention, RTCC running from LFXO	—	0.91	—	μA
		128 byte RAM retention, CRYOTIMER running from ULFRCO	—	0.35	—	μA
		128 byte RAM retention, no RTCC	—	0.35	—	μA
Current consumption in EM4S mode	I _{EM4S}	no RAM retention, no RTCC	—	0.04	—	μA

4.1.8.2 High-Frequency Crystal Oscillator (HFXO)

Table 4.11. High-Frequency Crystal Oscillator (HFXO)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Crystal frequency	f_{HFXO}		38	38.4	40	MHz
Supported crystal equivalent series resistance (ESR)	$\text{ESR}_{\text{HFXO}_38\text{M4}}$	Crystal frequency 38.4 MHz	—	—	60	Ω
Supported range of crystal load capacitance ¹	$C_{\text{HFXO_CL}}$		6	—	12	pF
On-chip tuning cap range ²	$C_{\text{HFXO_T}}$	On each of HFXTAL_N and HFXTAL_P pins	TBD	20	TBD	pF
On-chip tuning capacitance step	SS_{HFXO}		—	0.04	—	pF
Startup time	t_{HFXO}	38.4 MHz, ESR = 50 Ohm, C_L = 10 pF	—	300	—	μs
Frequency tolerance for the crystal	FT_{HFXO}	38.4 MHz, ESR = 50 Ohm, C_L = 10 pF	-40	—	40	ppm

Note:

1. Total load capacitance as seen by the crystal.
2. The effective load capacitance seen by the crystal will be $C_{\text{HFXO_T}}/2$. This is because each XTAL pin has a tuning cap and the two caps will be seen in series by the crystal. .

4.1.8.3 Low-Frequency RC Oscillator (LFRCO)

Table 4.12. Low-Frequency RC Oscillator (LFRCO)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Oscillation frequency	f_{LFRCO}	$\text{ENVREF}^2 = 1$	TBD	32.768	TBD	kHz
		$\text{ENVREF}^2 = 1$, $T_{\text{AMB}} > 85^\circ\text{C}$	TBD	32.768	TBD	kHz
		$\text{ENVREF}^2 = 0$	TBD	32.768	TBD	kHz
		$\text{ENVREF}^2 = 0$, $T_{\text{AMB}} > 85^\circ\text{C}$	TBD	32.768	TBD	kHz
Startup time	t_{LFRCO}		—	500	—	μs
Current consumption ¹	I_{LFRCO}	$\text{ENVREF} = 1$ in CMU_LFRCOCTRL	—	370	—	nA
		$\text{ENVREF} = 0$ in CMU_LFRCOCTRL	—	520	—	nA

Note:

1. Block is supplied by AVDD if ANASW = 0, or DVDD if ANASW=1 in EMU_PWRCTRL register.
2. in CMU_LFRCOCTRL register.

4.1.9 Flash Memory Characteristics³

Table 4.16. Flash Memory Characteristics³

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Flash erase cycles before failure	EC _{FLASH}		10000	—	—	cycles
Flash data retention	RET _{FLASH}	T _{AMB} ≤ 85 °C	10	—	—	years
		T _{AMB} ≤ 125 °C	10	—	—	years
Word (32-bit) programming time	t _{W_PROG}		20	24.4	30	μs
Page erase time	t _{PERASE}		20	26.4	35	ms
Mass erase time ¹	t _{MERASE}		20	26.5	35	ms
Device erase time ²	t _{DERASE}	T _{AMB} ≤ 85 °C	—	69	100	ms
		T _{AMB} ≤ 125 °C	—	69	110	ms
Page erase current ⁴	I _{ERASE}		—	—	1.6	mA
Write current ⁴	I _{WRITE}		—	—	3.8	mA
Supply voltage during flash erase and write	V _{FLASH}		1.62	—	TBD	V

Note:

1. Mass erase is issued by the CPU and erases all flash.
2. Device erase is issued over the AAP interface and erases all flash, SRAM, the Lock Bit (LB) page, and the User data page Lock Word (ULW).
3. Flash data retention information is published in the Quarterly Quality and Reliability Report.
4. Measured at 25 °C.

4.1.10 General-Purpose I/O (GPIO)

Table 4.17. General-Purpose I/O (GPIO)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input low voltage	V_{IL}	GPIO pins	—	—	$IOVDD \cdot 0.3$	V
Input high voltage	V_{IH}	GPIO pins	$IOVDD \cdot 0.7$	—	—	V
Output high voltage relative to IOVDD	V_{OH}	Sourcing 3 mA, $IOVDD \geq 3$ V, DRIVESTRENGTH ¹ = WEAK	$IOVDD \cdot 0.8$	—	—	V
		Sourcing 1.2 mA, $IOVDD \geq 1.62$ V, DRIVESTRENGTH ¹ = WEAK	$IOVDD \cdot 0.6$	—	—	V
		Sourcing 20 mA, $IOVDD \geq 3$ V, DRIVESTRENGTH ¹ = STRONG	$IOVDD \cdot 0.8$	—	—	V
		Sourcing 8 mA, $IOVDD \geq 1.62$ V, DRIVESTRENGTH ¹ = STRONG	$IOVDD \cdot 0.6$	—	—	V
Output low voltage relative to IOVDD	V_{OL}	Sinking 3 mA, $IOVDD \geq 3$ V, DRIVESTRENGTH ¹ = WEAK	—	—	$IOVDD \cdot 0.2$	V
		Sinking 1.2 mA, $IOVDD \geq 1.62$ V, DRIVESTRENGTH ¹ = WEAK	—	—	$IOVDD \cdot 0.4$	V
		Sinking 20 mA, $IOVDD \geq 3$ V, DRIVESTRENGTH ¹ = STRONG	—	—	$IOVDD \cdot 0.2$	V
		Sinking 8 mA, $IOVDD \geq 1.62$ V, DRIVESTRENGTH ¹ = STRONG	—	—	$IOVDD \cdot 0.4$	V
Input leakage current	I_{IOLEAK}	All GPIO except LFXO pins, GPIO $\leq IOVDD$, $T_{amb} \leq 85$ °C	—	0.1	TBD	nA
		LFXO Pins, GPIO $\leq IOVDD$, $T_{amb} \leq 85$ °C	—	0.1	TBD	nA
		All GPIO except LFXO pins, GPIO $\leq IOVDD$, $T_{AMB} > 85$ °C	—	—	TBD	nA
		LFXO Pins, GPIO $\leq IOVDD$, $T_{AMB} > 85$ °C	—	—	TBD	nA
Input leakage current on 5VTOL pads above IOVDD	$I_{5VTOLLEAK}$	$IOVDD < GPIO \leq IOVDD + 2$ V	—	3.3	15	μ A
I/O pin pull-up/pull-down resistor	R_{PUD}		TBD	43	TBD	k Ω
Pulse width of pulses removed by the glitch suppression filter	$t_{IOGLITCH}$		TBD	25	TBD	ns

4.1.15 Current Digital to Analog Converter (IDAC)

Table 4.22. Current Digital to Analog Converter (IDAC)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Number of ranges	N _{IDAC_RANGES}		—	4	—	-
Output current	I _{IDAC_OUT}	RANGSEL ¹ = RANGE0	0.05	—	1.6	μA
		RANGSEL ¹ = RANGE1	1.6	—	4.7	μA
		RANGSEL ¹ = RANGE2	0.5	—	16	μA
		RANGSEL ¹ = RANGE3	2	—	64	μA
Linear steps within each range	N _{IDAC_STEPS}		—	32	—	
Step size	SS _{IDAC}	RANGSEL ¹ = RANGE0	—	50	—	nA
		RANGSEL ¹ = RANGE1	—	100	—	nA
		RANGSEL ¹ = RANGE2	—	500	—	nA
		RANGSEL ¹ = RANGE3	—	2	—	μA
Total accuracy, STEPSEL ¹ = 0x80	ACC _{IDAC}	EM0 or EM1, AVDD=3.3 V, T = 25 °C	TBD	—	TBD	%
		EM0 or EM1	TBD	—	TBD	%
		EM2 or EM3, Source mode, RANGSEL ¹ = RANGE0, AVDD=3.3 V, T = 25 °C	—	-2	—	%
		EM2 or EM3, Source mode, RANGSEL ¹ = RANGE1, AVDD=3.3 V, T = 25 °C	—	-1.7	—	%
		EM2 or EM3, Source mode, RANGSEL ¹ = RANGE2, AVDD=3.3 V, T = 25 °C	—	-0.8	—	%
		EM2 or EM3, Source mode, RANGSEL ¹ = RANGE3, AVDD=3.3 V, T = 25 °C	—	-0.5	—	%
		EM2 or EM3, Sink mode, RANGSEL ¹ = RANGE0, AVDD=3.3 V, T = 25 °C	—	-0.7	—	%
		EM2 or EM3, Sink mode, RANGSEL ¹ = RANGE1, AVDD=3.3 V, T = 25 °C	—	-0.6	—	%
		EM2 or EM3, Sink mode, RANGSEL ¹ = RANGE2, AVDD=3.3 V, T = 25 °C	—	-0.5	—	%
		EM2 or EM3, Sink mode, RANGSEL ¹ = RANGE3, AVDD=3.3 V, T = 25 °C	—	-0.5	—	%
Start up time	t _{IDAC_SU}	Output within 1% of steady state value	—	5	—	μs

Pin		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
A4	PC3	BUSAY BUSBX	WTIM0_CC0 #23 WTIM0_CC1 #21 WTIM0_CC2 #19 WTIM0_CDTI0 #15 WTIM0_CDTI1 #13 WTIM0_CDTI2 #11 WTIM1_CC0 #7 WTIM1_CC1 #5 WTIM1_CC2 #3 WTIM1_CC3 #1 PCNT1_S0IN #16 PCNT1_S1IN #15 PCNT2_S0IN #16 PCNT2_S1IN #15	US3_TX #21 US3_RX #20 US3_CLK #19 US3_CS #18 US3_CTS #17 US3_RTS #16 I2C1_SDA #16 I2C1_SCL #15	
A5	PC0	BUSBY BUSAX	WTIM0_CC0 #20 WTIM0_CC1 #18 WTIM0_CC2 #16 WTIM0_CDTI0 #12 WTIM0_CDTI1 #10 WTIM0_CDTI2 #8 WTIM1_CC0 #4 WTIM1_CC1 #2 WTIM1_CC2 #0 PCNT1_S0IN #13 PCNT1_S1IN #12 PCNT2_S0IN #13 PCNT2_S1IN #12	US3_TX #18 US3_RX #17 US3_CLK #16 US3_CS #15 US3_CTS #14 US3_RTS #13 I2C1_SDA #13 I2C1_SCL #12	
A6	PC11	BUSAY BUSBX	TIM0_CC0 #16 TIM0_CC1 #15 TIM0_CC2 #14 TIM0_CDTI0 #13 TIM0_CDTI1 #12 TIM0_CDTI2 #11 TIM1_CC0 #16 TIM1_CC1 #15 TIM1_CC2 #14 TIM1_CC3 #13 WTIM0_CC0 #31 WTIM0_CC1 #29 WTIM0_CC2 #27 WTIM0_CDTI0 #23 WTIM0_CDTI1 #21 WTIM0_CDTI2 #19 WTIM1_CC0 #15 WTIM1_CC1 #13 WTIM1_CC2 #11 WTIM1_CC3 #9 LE- TIM0_OUT0 #16 LE- TIM0_OUT1 #15 PCNT0_S0IN #16 PCNT0_S1IN #15 PCNT2_S0IN #20 PCNT2_S1IN #19	US0_TX #16 US0_RX #15 US0_CLK #14 US0_CS #13 US0_CTS #12 US0_RTS #11 US1_TX #16 US1_RX #15 US1_CLK #14 US1_CS #13 US1_CTS #12 US1_RTS #11 LEU0_TX #16 LEU0_RX #15 I2C0_SDA #16 I2C0_SCL #15 I2C1_SDA #20 I2C1_SCL #19	CMU_CLK0 #3 PRS_CH0 #13 PRS_CH9 #16 PRS_CH10 #5 PRS_CH11 #4 ACMP0_O #16 ACMP1_O #16 DBG_SWO #3

Pin		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
C1	PF11	BUSAY BUSBX	WTIM1_CC2 #31 WTIM1_CC3 #29 PCNT1_S0IN #24 PCNT1_S1IN #23 PCNT2_S0IN #24 PCNT2_S1IN #23	US2_TX #24 US2_RX #23 US2_CLK #22 US2_CS #21 US2_CTS #20 US2_RTS #19 US3_TX #24 US3_RX #23 US3_CLK #22 US3_CS #21 US3_CTS #20 US3_RTS #19 I2C1_SDA #24 I2C1_SCL #23	ETM_TD2 #0
C2	PF10	BUSBY BUSAX	WTIM1_CC2 #30 WTIM1_CC3 #28 PCNT1_S0IN #23 PCNT1_S1IN #22 PCNT2_S0IN #23 PCNT2_S1IN #22	US2_TX #23 US2_RX #22 US2_CLK #21 US2_CS #20 US2_CTS #19 US2_RTS #18 I2C1_SDA #23 I2C1_SCL #22	ETM_TD1 #0
C3	PF9	BUSAY BUSBX	WTIM1_CC1 #31 WTIM1_CC2 #29 WTIM1_CC3 #27 PCNT1_S0IN #22 PCNT1_S1IN #21 PCNT2_S0IN #22 PCNT2_S1IN #21	US2_TX #22 US2_RX #21 US2_CLK #20 US2_CS #19 US2_CTS #18 US2_RTS #17 I2C1_SDA #22 I2C1_SCL #21	ETM_TD0 #0
C5	PC2	BUSBY BUSAX	WTIM0_CC0 #22 WTIM0_CC1 #20 WTIM0_CC2 #18 WTIM0_CDTI0 #14 WTIM0_CDTI1 #12 WTIM0_CDTI2 #10 WTIM1_CC0 #6 WTIM1_CC1 #4 WTIM1_CC2 #2 WTIM1_CC3 #0 PCNT1_S0IN #15 PCNT1_S1IN #14 PCNT2_S0IN #15 PCNT2_S1IN #14	US3_TX #20 US3_RX #19 US3_CLK #18 US3_CS #17 US3_CTS #16 US3_RTS #15 I2C1_SDA #15 I2C1_SCL #14	
C6	PJ15	BUSACMP1Y BUSACMP1X	PCNT1_S0IN #12 PCNT1_S1IN #11 PCNT2_S0IN #12 PCNT2_S1IN #11	US3_TX #17 US3_RX #16 US3_CLK #15 US3_CS #14 US3_CTS #13 US3_RTS #12 I2C1_SDA #12 I2C1_SCL #11	LES_ALTEX3

Pin		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
6	PF5	BUSAY BUSBX	TIM0_CC0 #29 TIM0_CC1 #28 TIM0_CC2 #27 TIM0_CDTI0 #26 TIM0_CDTI1 #25 TIM0_CDTI2 #24 TIM1_CC0 #29 TIM1_CC1 #28 TIM1_CC2 #27 TIM1_CC3 #26 WTIM1_CC0 #29 WTIM1_CC1 #27 WTIM1_CC2 #25 WTIM1_CC3 #23 LE- TIM0_OUT0 #29 LE- TIM0_OUT1 #28 PCNT0_S0IN #29 PCNT0_S1IN #28	US0_TX #29 US0_RX #28 US0_CLK #27 US0_CS #26 US0_CTS #25 US0_RTS #24 US1_TX #29 US1_RX #28 US1_CLK #27 US1_CS #26 US1_CTS #25 US1_RTS #24 US2_TX #18 US2_RX #17 US2_CLK #16 US2_CS #15 US2_CTS #14 US2_RTS #13 LEU0_TX #29 LEU0_RX #28 I2C0_SDA #29 I2C0_SCL #28	PRS_CH0 #5 PRS_CH1 #4 PRS_CH2 #3 PRS_CH3 #2 ACMP0_O #29 ACMP1_O #29
7	PF6	BUSBY BUSAX	TIM0_CC0 #30 TIM0_CC1 #29 TIM0_CC2 #28 TIM0_CDTI0 #27 TIM0_CDTI1 #26 TIM0_CDTI2 #25 TIM1_CC0 #30 TIM1_CC1 #29 TIM1_CC2 #28 TIM1_CC3 #27 WTIM1_CC0 #30 WTIM1_CC1 #28 WTIM1_CC2 #26 WTIM1_CC3 #24 LE- TIM0_OUT0 #30 LE- TIM0_OUT1 #29 PCNT0_S0IN #30 PCNT0_S1IN #29 PCNT1_S0IN #19 PCNT1_S1IN #18	US0_TX #30 US0_RX #29 US0_CLK #28 US0_CS #27 US0_CTS #26 US0_RTS #25 US1_TX #30 US1_RX #29 US1_CLK #28 US1_CS #27 US1_CTS #26 US1_RTS #25 US2_TX #19 US2_RX #18 US2_CLK #17 US2_CS #16 US2_CTS #15 US2_RTS #14 LEU0_TX #30 LEU0_RX #29 I2C0_SDA #30 I2C0_SCL #29	CMU_CLK1 #7 PRS_CH0 #6 PRS_CH1 #5 PRS_CH2 #4 PRS_CH3 #3 ACMP0_O #30 ACMP1_O #30
8	PF7	BUSAY BUSBX	TIM0_CC0 #31 TIM0_CC1 #30 TIM0_CC2 #29 TIM0_CDTI0 #28 TIM0_CDTI1 #27 TIM0_CDTI2 #26 TIM1_CC0 #31 TIM1_CC1 #30 TIM1_CC2 #29 TIM1_CC3 #28 WTIM1_CC0 #31 WTIM1_CC1 #29 WTIM1_CC2 #27 WTIM1_CC3 #25 LE- TIM0_OUT0 #31 LE- TIM0_OUT1 #30 PCNT0_S0IN #31 PCNT0_S1IN #30 PCNT1_S0IN #20 PCNT1_S1IN #19	US0_TX #31 US0_RX #30 US0_CLK #29 US0_CS #28 US0_CTS #27 US0_RTS #26 US1_TX #31 US1_RX #30 US1_CLK #29 US1_CS #28 US1_CTS #27 US1_RTS #26 US2_TX #20 US2_RX #19 US2_CLK #18 US2_CS #17 US2_CTS #16 US2_RTS #15 LEU0_TX #31 LEU0_RX #30 I2C0_SDA #31 I2C0_SCL #30	CMU_CLKI0 #1 CMU_CLK0 #7 PRS_CH0 #7 PRS_CH1 #6 PRS_CH2 #5 PRS_CH3 #4 ACMP0_O #31 ACMP1_O #31 GPIO_EM4WU1
9	AVDD	Analog power supply .			

Pin		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
45	PC8	BUSBY BUSAX	TIM0_CC0 #13 TIM0_CC1 #12 TIM0_CC2 #11 TIM0_CDTI0 #10 TIM0_CDTI1 #9 TIM0_CDTI2 #8 TIM1_CC0 #13 TIM1_CC1 #12 TIM1_CC2 #11 TIM1_CC3 #10 WTIM0_CC0 #28 WTIM0_CC1 #26 WTIM0_CC2 #24 WTIM0_CDTI0 #20 WTIM0_CDTI1 #18 WTIM0_CDTI2 #16 WTIM1_CC0 #12 WTIM1_CC1 #10 WTIM1_CC2 #8 WTIM1_CC3 #6 LE- TIM0_OUT0 #13 LE- TIM0_OUT1 #12 PCNT0_S0IN #13 PCNT0_S1IN #12	US0_TX #13 US0_RX #12 US0_CLK #11 US0_CS #10 US0_CTS #9 US0_RTS #8 US1_TX #13 US1_RX #12 US1_CLK #11 US1_CS #10 US1_CTS #9 US1_RTS #8 LEU0_TX #13 LEU0_RX #12 I2C0_SDA #13 I2C0_SCL #12	PRS_CH0 #10 PRS_CH9 #13 PRS_CH10 #2 PRS_CH11 #1 ACMP0_O #13 ACMP1_O #13 ETM_TD1
46	PC9	BUSAY BUSBX	TIM0_CC0 #14 TIM0_CC1 #13 TIM0_CC2 #12 TIM0_CDTI0 #11 TIM0_CDTI1 #10 TIM0_CDTI2 #9 TIM1_CC0 #14 TIM1_CC1 #13 TIM1_CC2 #12 TIM1_CC3 #11 WTIM0_CC0 #29 WTIM0_CC1 #27 WTIM0_CC2 #25 WTIM0_CDTI0 #21 WTIM0_CDTI1 #19 WTIM0_CDTI2 #17 WTIM1_CC0 #13 WTIM1_CC1 #11 WTIM1_CC2 #9 WTIM1_CC3 #7 LE- TIM0_OUT0 #14 LE- TIM0_OUT1 #13 PCNT0_S0IN #14 PCNT0_S1IN #13	US0_TX #14 US0_RX #13 US0_CLK #12 US0_CS #11 US0_CTS #10 US0_RTS #9 US1_TX #14 US1_RX #13 US1_CLK #12 US1_CS #11 US1_CTS #10 US1_RTS #9 LEU0_TX #14 LEU0_RX #13 I2C0_SDA #14 I2C0_SCL #13	PRS_CH0 #11 PRS_CH9 #14 PRS_CH10 #3 PRS_CH11 #2 ACMP0_O #14 ACMP1_O #14 ETM_TD2

Alternate	LOCATION								
Functionality	0 - 3	4 - 7	8 - 11	12 - 15	16 - 19	20 - 23	24 - 27	28 - 31	Description
DBG_SWCLKTCK	0: PF0								Debug-interface Serial Wire clock input and JTAG Test Clock. Note that this function is enabled to the pin out of reset, and has a built-in pull down.
DBG_SWDIOTMS	0: PF1								Debug-interface Serial Wire data input / output and JTAG Test Mode Select. Note that this function is enabled to the pin out of reset, and has a built-in pull up.
DBG_SWO	0: PF2 1: PB13 2: PD15 3: PC11								Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
DBG_TDI	0: PF3								Debug-interface JTAG Test Data In. Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_TDO	0: PF2								Debug-interface JTAG Test Data Out. Note that this function is enabled to pin out of reset.
ETM_TCLK	0: PF8 1: PA5 2: PI2 3: PC6								Embedded Trace Module ETM clock .
ETM_TD0	0: PF9 1: PA6 2: PI3 3: PC7								Embedded Trace Module ETM data 0.
ETM_TD1	0: PF10 1: PA7 2: PB6 3: PC8								Embedded Trace Module ETM data 1.

Alternate	LOCATION								
Functionality	0 - 3	4 - 7	8 - 11	12 - 15	16 - 19	20 - 23	24 - 27	28 - 31	Description
ETM_TD2	0: PF11 1: PA8 2: PB7 3: PC9								Embedded Trace Module ETM data 2.
ETM_TD3	0: PF12 1: PA9 2: PB8 3: PC10								Embedded Trace Module ETM data 3.
GPIO_EM4WU0	0: PF2								Pin can be used to wake the system up from EM4
GPIO_EM4WU1	0: PF7								Pin can be used to wake the system up from EM4
GPIO_EM4WU4	0: PD14								Pin can be used to wake the system up from EM4
GPIO_EM4WU8	0: PA3								Pin can be used to wake the system up from EM4
GPIO_EM4WU9	0: PB13								Pin can be used to wake the system up from EM4
GPIO_EM4WU12	0: PC10								Pin can be used to wake the system up from EM4
I2C0_SCL	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	16: PD9 17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	I2C0 Serial Clock Line input / output.
I2C0_SDA	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 17: PD9 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	I2C0 Serial Data input / output.
I2C1_SCL	0: PA7 1: PA8 2: PA9 3: PI2	4: PI3 5: PB6 6: PB7 7: PB8	8: PB9 9: PB10 10: PJ14 11: PJ15	12: PC0 13: PC1 14: PC2 15: PC3	16: PC4 17: PC5 18: PC10 19: PC11	20: PF8 21: PF9 22: PF10 23: PF11	24: PF12 25: PF13 26: PF14 27: PF15	28: PK0 29: PK1 30: PK2 31: PA6	I2C1 Serial Clock Line input / output.
I2C1_SDA	0: PA6 1: PA7 2: PA8 3: PA9	4: PI2 5: PI3 6: PB6 7: PB7	8: PB8 9: PB9 10: PB10 11: PJ14	12: PJ15 13: PC0 14: PC1 15: PC2	16: PC3 17: PC4 18: PC5 19: PC10	20: PC11 21: PF8 22: PF9 23: PF10	24: PF11 25: PF12 26: PF13 27: PF14	28: PF15 29: PK0 30: PK1 31: PK2	I2C1 Serial Data input / output.
IDAC0_OUT	0: PK0								IDAC0 output.

Alternate	LOCATION								
Functionality	0 - 3	4 - 7	8 - 11	12 - 15	16 - 19	20 - 23	24 - 27	28 - 31	Description
US1_RTS	0: PA5 1: PB11 2: PB12 3: PB13	4: PB14 5: PB15 6: PC6 7: PC7	8: PC8 9: PC9 10: PC10 11: PC11	12: PD9 13: PD10 14: PD11 15: PD12	16: PD13 17: PD14 18: PD15 19: PF0	20: PF1 21: PF2 22: PF3 23: PF4	24: PF5 25: PF6 26: PF7 27: PA0	28: PA1 29: PA2 30: PA3 31: PA4	USART1 Request To Send hardware flow control output.
US1_RX	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	16: PD9 17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 17: PD9 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	USART1 Asynchronous Transmit. Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
US2_CLK	0: PA7 1: PA8 2: PA9 3: PI0	4: PI1 5: PI2 6: PI3 7: PB6	8: PB7 9: PB8 10: PB9 11: PB10	12: PF0 13: PF1 14: PF3 15: PF4	16: PF5 17: PF6 18: PF7 19: PF8	20: PF9 21: PF10 22: PF11 23: PF12	24: PF13 25: PF14 26: PF15 27: PK0	28: PK1 29: PK2 30: PA5 31: PA6	USART2 clock input / output.
US2_CS	0: PA8 1: PA9 2: PI0 3: PI1	4: PI2 5: PI3 6: PB6 7: PB7	8: PB8 9: PB9 10: PB10 11: PF0	12: PF1 13: PF3 14: PF4 15: PF5	16: PF6 17: PF7 18: PF8 19: PF9	20: PF10 21: PF11 22: PF12 23: PF13	24: PF14 25: PF15 26: PK0 27: PK1	28: PK2 29: PA5 30: PA6 31: PA7	USART2 chip select input / output.
US2_CTS	0: PA9 1: PI0 2: PI1 3: PI2	4: PI3 5: PB6 6: PB7 7: PB8	8: PB9 9: PB10 10: PF0 11: PF1	12: PF3 13: PF4 14: PF5 15: PF6	16: PF7 17: PF8 18: PF9 19: PF10	20: PF11 21: PF12 22: PF13 23: PF14	24: PF15 25: PK0 26: PK1 27: PK2	28: PA5 29: PA6 30: PA7 31: PA8	USART2 Clear To Send hardware flow control input.
US2_RTS	0: PI0 1: PI1 2: PI2 3: PI3	4: PB6 5: PB7 6: PB8 7: PB9	8: PB10 9: PF0 10: PF1 11: PF3	12: PF4 13: PF5 14: PF6 15: PF7	16: PF8 17: PF9 18: PF10 19: PF11	20: PF12 21: PF13 22: PF14 23: PF15	24: PK0 25: PK1 26: PK2 27: PA5	28: PA6 29: PA7 30: PA8 31: PA9	USART2 Request To Send hardware flow control output.
US2_RX	0: PA6 1: PA7 2: PA8 3: PA9	4: PI0 5: PI1 6: PI2 7: PI3	8: PB6 9: PB7 10: PB8 11: PB9	12: PB10 13: PF0 14: PF1 15: PF3	16: PF4 17: PF5 18: PF6 19: PF7	20: PF8 21: PF9 22: PF10 23: PF11	24: PF12 25: PF13 26: PF14 27: PF15	28: PK0 29: PK1 30: PK2 31: PA5	USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).
US2_TX	0: PA5 1: PA6 2: PA7 3: PA8	4: PA9 5: PI0 6: PI1 7: PI2	8: PI3 9: PB6 10: PB7 11: PB8	12: PB9 13: PB10 14: PF0 15: PF1	16: PF3 17: PF4 18: PF5 19: PF6	20: PF7 21: PF8 22: PF9 23: PF10	24: PF11 25: PF12 26: PF13 27: PF14	28: PF15 29: PK0 30: PK1 31: PK2	USART2 Asynchronous Transmit. Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).

Table 6.7. ACMP1 Bus and Pin Mapping

APORT4Y	APORT4X	APORT3Y	APORT3X	APORT2Y	APORT2X	APORT1Y	APORT1X	APORT0Y	APORT0X	Port
BUSDY	BUSDX	BUSCY	BUSCX	BUSBY	BUSBX	BUSAY	BUSAX	BUSACMP1Y	BUSACMP1X	Bus
PB14	PB15	PB15	PB14	PF14	PF15	PF15	PF14			CH31
	PB13	PB13			PF13	PF13				CH30
PB12			PB12	PF12			PF12			CH29
	PB11	PB11			PF11	PF11				CH28
PB10			PB10	PF10			PF10			CH27
	PB9	PB9			PF9	PF9				CH26
PB8			PB8	PF8			PF8			CH25
	PB7	PB7			PF7	PF7				CH24
PB6			PB6	PF6			PF6			CH23
					PF5	PF5				CH22
				PF4			PF4			CH21
					PF3	PF3				CH20
				PF2			PF2			CH19
					PF1	PF1				CH18
				PF0			PF0			CH17
	PA7	PA7								CH16
PA6			PA6							CH15
	PA5	PA5								CH14
PA4			PA4							CH13
	PA3	PA3			PC11	PC11				CH12
PA2			PA2	PC10			PC10			CH11
	PA1	PA1			PC9	PC9				CH10
PA0			PA0	PC8			PC8			CH9
	PD15	PD15			PC7	PC7		PJ15	PJ15	CH8
PD14			PD14	PC6			PC6	PJ14	PJ14	CH7
	PD13	PD13			PC5	PC5				CH6
PD12			PD12	PC4			PC4			CH5
	PD11	PD11			PC3	PC3				CH4
PD10			PD10	PC2			PC2			CH3
	PD9	PD9			PC1	PC1				CH2
PD8			PD8	PC0			PC0			CH1
										CH0

7.3 BGA125 Package Marking



Figure 7.3. BGA125 Package Marking

The package marking consists of:

- P P P P P P P P P P – The part number designation.
- T T T T T T – A trace or manufacturing code. The first letter is the device revision.
- Y Y – The last 2 digits of the assembly year.
- W W – The 2-digit workweek when the device was assembled.

Table 8.1. QFN48 Package Dimensions

Dimension	Min	Typ	Max
A	0.80	0.85	0.90
A1	0.00	0.02	0.05
A3	0.20 REF		
b	0.18	0.25	0.30
D	6.90	7.00	7.10
E	6.90	7.00	7.10
D2	5.15	5.30	5.45
E2	5.15	5.30	5.45
e	0.50 BSC		
L	0.30	0.40	0.50
K	0.20	—	—
R	0.09	—	—
aaa	0.15		
bbb	0.10		
ccc	0.10		
ddd	0.05		
eee	0.08		
fff	0.10		

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. This drawing conforms to the JEDEC Solid State Outline MO-220, Variation VKKD-4.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

6. Pin Definitions

6.1 EFM32PG12B5xx in BGA125 Device Pinout

6.1.1 EFM32PG12B5xx in BGA125 GPIO Overview

6.2 EFM32PG12B5xx in QFN48 Device Pinout

6.2.1 EFM32PG12B5xx in QFN48 GPIO Overview

6.3 Alternate Functionality Overview

6.4 Analog Port (APORT) Client Maps

7. BGA125 Package Specifications

7.1 BGA125 Package Dimensions

7.2 BGA125 PCB Land Pattern

7.3 BGA125 Package Marking

8. QFN48 Package Specifications.

8.1 QFN48 Package Dimensions.

8.2 QFN48 PCB Land Pattern.

8.3 QFN48 Package Marking

9. Revision History

9.1 Revision 0.5

9.2 Revision 0.2

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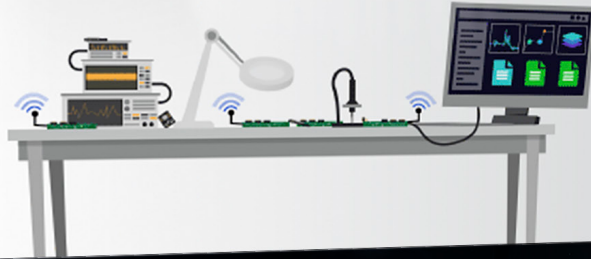
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